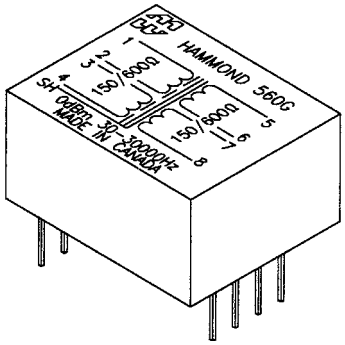
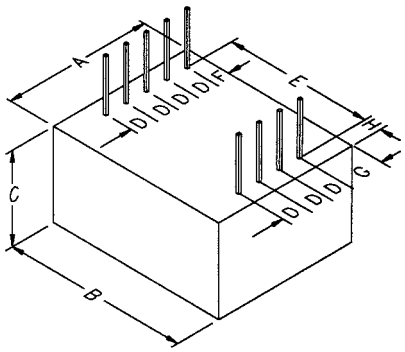






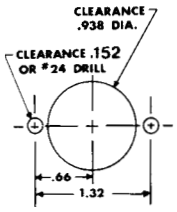
P.C. BOARD MOUNT - EPOXY POTTED AUDIO TRANSFORMERS

- Rugged black epoxy potted case with 9 pin connections (.025" square by 0.5" long).
- Frequency response @ 0 dbm +/- 1 db max. (+/- 0.5 db is typical) of 30 Hz. to 30 Khz., except 560Q which is 30 Hz. to 15 Khz.
- Insertion loss of 1 db max.
- Maximum power level 0 dbm.
- Electrostatic shield between primary & secondary connected to core and pin "SH".
- Humbucking construction
- Balanced split windings on primary & secondary for circuit versatility.
- Primaries and secondaries can be reversed for impedance matching.
- Overall dimensions 1.64" x 1.33" x 0.85" high max.
- Shipping weight 4 oz.

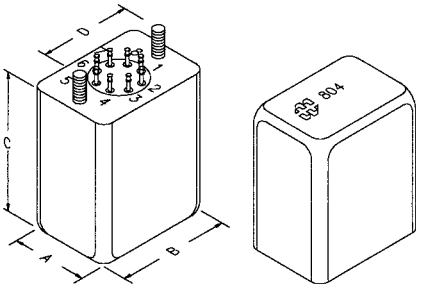
Part No.	Application	Nominal Impedance	
		Primary	Secondary
560C	Emitter or mic to Line	12/48	150/600
560E	Emitter or mic to Line	50/200	150/600
560G	Isolating or Hybrid	150/600	150/600
560J	Collector to Line or Line to Base	150/600	1200/4800
560L	Collector to Line or Matching	150/600	5K/20K
560N	Collector to Line	150/600	10K/40K
560Q	Matching or Bridging	10k/40k	10K/40K

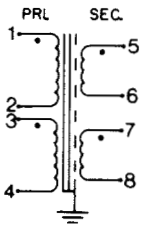
Dimensions (Inches)							
A	B	C	D	E	F	G	H
1.33	1.64	0.85 Max.	0.20	1.30	0.141	0.344	0.156





Base Outline





CHASSIS MOUNT - HERMETICALLY SEALED AUDIO TRANSFORMERS

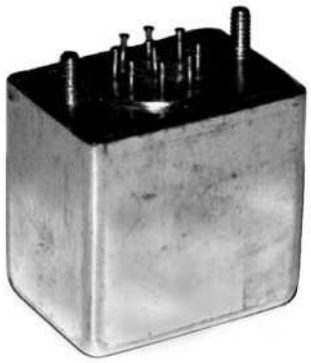
- Deep-drawn steel case with tin plated finish, with two convenient 6-32 mounting studs with hardware.
- Hermetically sealed for stable characteristics and long life. Header has nine 0.22" long solder pins.
- Frequency response +/- 0.5 db max. from 50 Hz. to 15 Khz.
- Insertion loss of apx. 1 db.
- Maximum power level +15 dbm. (except 841, 842 & 844 which are +20 dbm) with specified characteristics, or higher levels with reduced low frequency performance.
- Electrostatic shield between primary & secondary connected to terminal 9.
- Humbucking construction
- Balanced split windings on primary & secondary for circuit versatility. Primary may be used as a secondary and vice versa for impedance matching.
- Overall dimensions 1.75" wide x 1.25" deep x 2.56" high max.
- Shipping weight 0.5 lb.

CHASSIS MOUNT - HERMETICALLY SEALED AUDIO TRANSFORMERS *(continued)*

Part No.	Application	Nominal Impedance		Max. Pri. D.C. Unbalanced ma
		Primary	Secondary	
801	Isolating, Matching	*50/200	50/200	0.8
802	Isolating, Matching	*50/200 (60/240)	125/500 (150/600)	0.8
804	Isolating, Matching, Hybrid	*125/500 (150/600)	125/500 (150/600)	0.5
806	Dynamic MIC or Voice Coil to Grid	*7.5/30	10K/40K	1.6
807	Dynamic MIC or Voice Coil to Base	*7.5/30	600/2400	1.6
808	MIC or Mixer to Single or P.P. Grid	*50/200	10000/40000	0.6
809	MIC to Mixer to Base	*50/200	600/2400	0.6
812	Line or 150 ohm MIC to 1 or 2 grids	*125/500 (150/600)	10K/40K (12K/48K)	0.4
813	Line or 150 ohm MIC to Base	*125/500 (150/600)	600/2400 (720/2880)	0.4
832	Interstage (ratio 1:2)	5K/20K	20K/80K	0
834	Interstage (ratio 1:4)	5K/20K	10K/40K	0
835	Interstage (ratio 1:1)	10K/40K	10K/40K	0
841	** P.P. Plates to Line	5K/20K	50/200	0
842	** P.P. Plates to Line	5K/20K (6K/24K)	125/500 (150/600)	0
844	** P.P. Plates to Line	10K/40K (12K/48K)	125/500 (150/600)	0

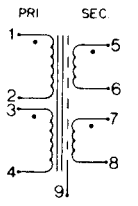
NOTES:
**** Electrostatic shield between primary & secondary***

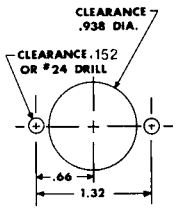
***** Single plate requires parallel feed. When operating at impedances below nominal, power capability is lower and the frequency spectrum is shifted downward, conversely, at higher impedances power capability and frequency spectrum will be shifted upward.***



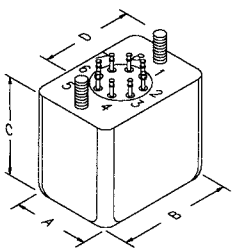
CHASSIS MOUNT - HERMETICALLY SEALED AUDIO TRANSFORMERS

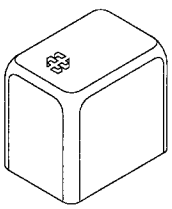
- Deep-drawn steel case with tin plated finish, with two convenient 6-32 mounting studs with hardware (same as 800 series except low profile).
- Hermetically sealed for stable characteristics and long life. Header has nine 0.22" long solder terminals.
- Frequency response +/- 0.5 db max. from 20 Hz. to 20 Khz., except units over 5K ohms impedance, may be down 1 db @ 20 Khz.
- Insertion loss of apx. 1 db.
- Maximum power level +15 dbm. with specified characteristics, or higher levels with reduced low frequency performance.
- Distortion is apx. 1.5% @ 20 Hz. under full power.
- Electrostatic shield between primary & secondary connected to terminal 9.
- Humbucking construction
- Balanced split windings on primary & secondary for circuit versatility. Primary may be used as a secondary and vice versa for impedance matching.
- Overall dimensions 1.7" x 1.2" x 1.65" high max.
- Shipping weight 0.4 lb.





Base Outline





Part No.	Application	Nominal Impedance		Nominal Resistance +/- 20%	
		Primary	Secondary	Primary	Secondary
850C	Emitter or MIC to Line	12/48	150/600	6	70
850E	Emitter or MIC to Line	50/200	150/600	27	68
850G	Line Isolation or Hybrid	150/600	150/600	71	71
850H	Line Isolation or Hybrid	150/600	300/1200	70	140
850J	Output to Line, or Line to Base	150/600	1200/4800	69	570
850L	Output to Line, Matching or Bridging	5K/20K	150/600	2240	69
850N	Output to Line, Matching or Interstage	150/600	10K/40K	65	4980
850Q	Interstage or Isolating	10K/40K	10K/40K	4890	4980